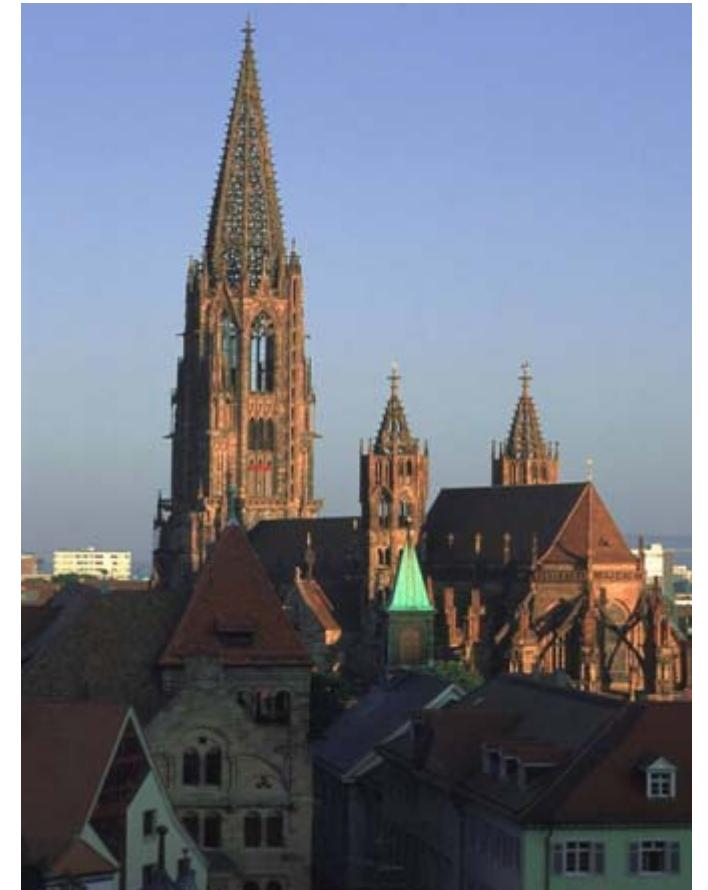


# Multiphysics Simulation of Thermoelectric Systems

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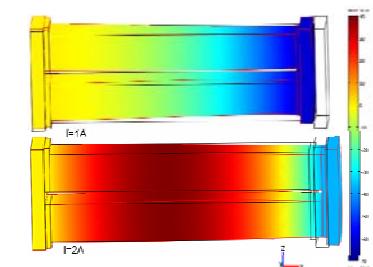
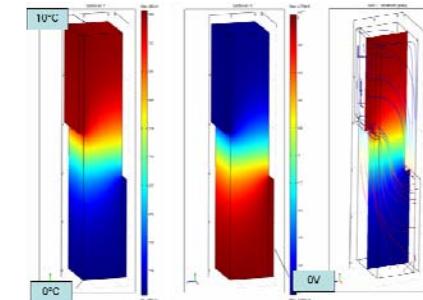


# Contents

$$\begin{aligned}-\vec{\nabla}((\sigma\alpha^2 T + \lambda)\vec{\nabla}T) - \vec{\nabla}(\sigma\alpha T \vec{\nabla}V) &= \sigma((\vec{\nabla}V)^2 + \alpha\vec{\nabla}T \vec{\nabla}V) \\ \vec{\nabla}(\sigma\alpha\vec{\nabla}T) + \vec{\nabla}(\sigma\vec{\nabla}V) &= 0\end{aligned}$$

$$\begin{aligned}\sigma \frac{\partial^2 u}{\partial x^2} + d_\sigma \frac{\partial u}{\partial t} + \nabla \cdot (-c\nabla u - \alpha u + \gamma) + \beta \cdot \nabla u + \alpha u &= f \quad \text{in } \Omega \\ n \cdot (-c\nabla u - \alpha u + \gamma) + q u &= g - k^T \mu \quad \text{on } \partial\Omega \\ h u &= r \quad \text{on } \partial\Omega\end{aligned}$$

1. Introduction
2. Equations to solve
3. Implementation in COMSOL
4. Thermoelectric modeling
5. Thermo-electric-mechanic calculations



# Introduction

Seebeck-Effect



$$\alpha = \Delta V / \Delta T$$

T. Seebeck (1821)

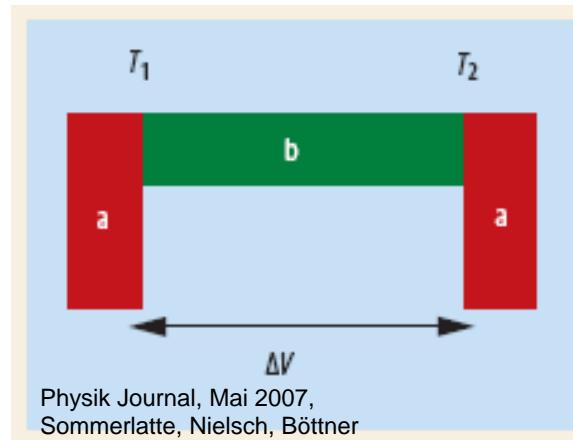
Peltier-Effect



$$Q = \Pi * I$$

$$\Pi = \alpha * T$$

J. C. A. Peltier (1834)



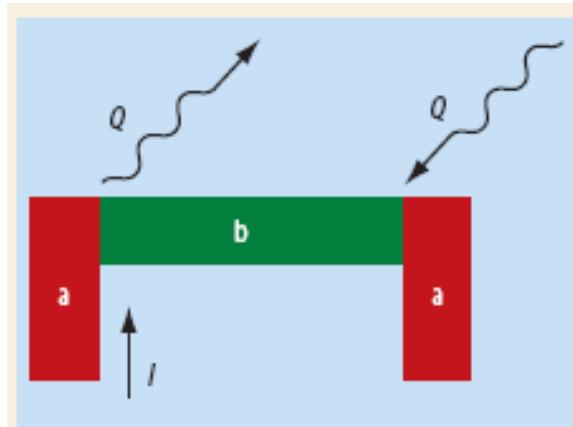
Thermoelectric Figure of Merit Z

$$Z = \frac{\sigma \alpha^2}{\lambda}$$

$\alpha$ : Seebeck Coefficient

$\Pi$ : Peltier Coefficient

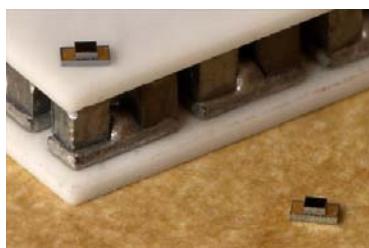
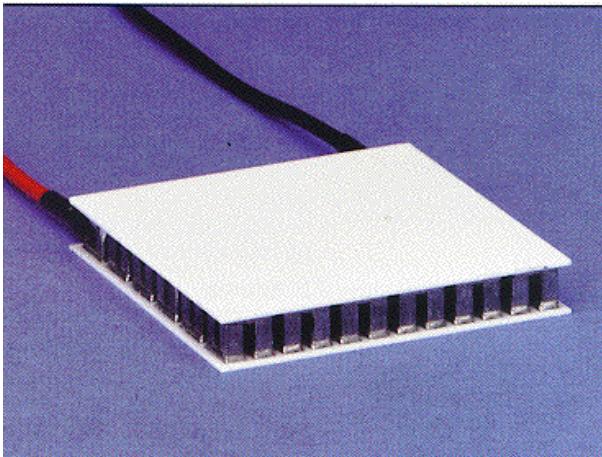
$\sigma, \lambda$ : electrical and thermal conductivities



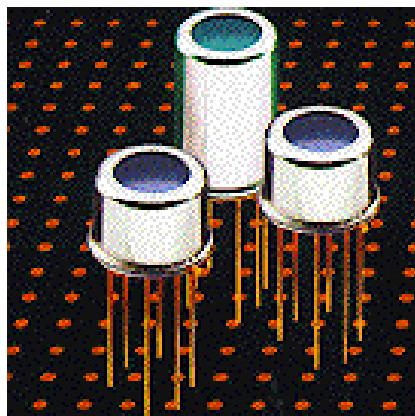
# Introduction

## Applications of Thermoelectrics

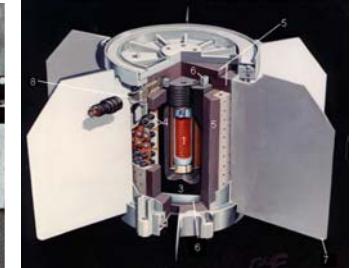
Coolers

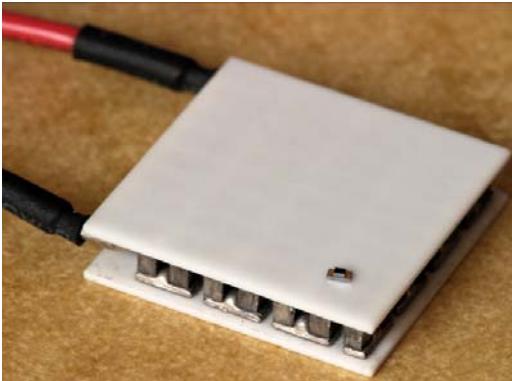


Detectors, Sensors

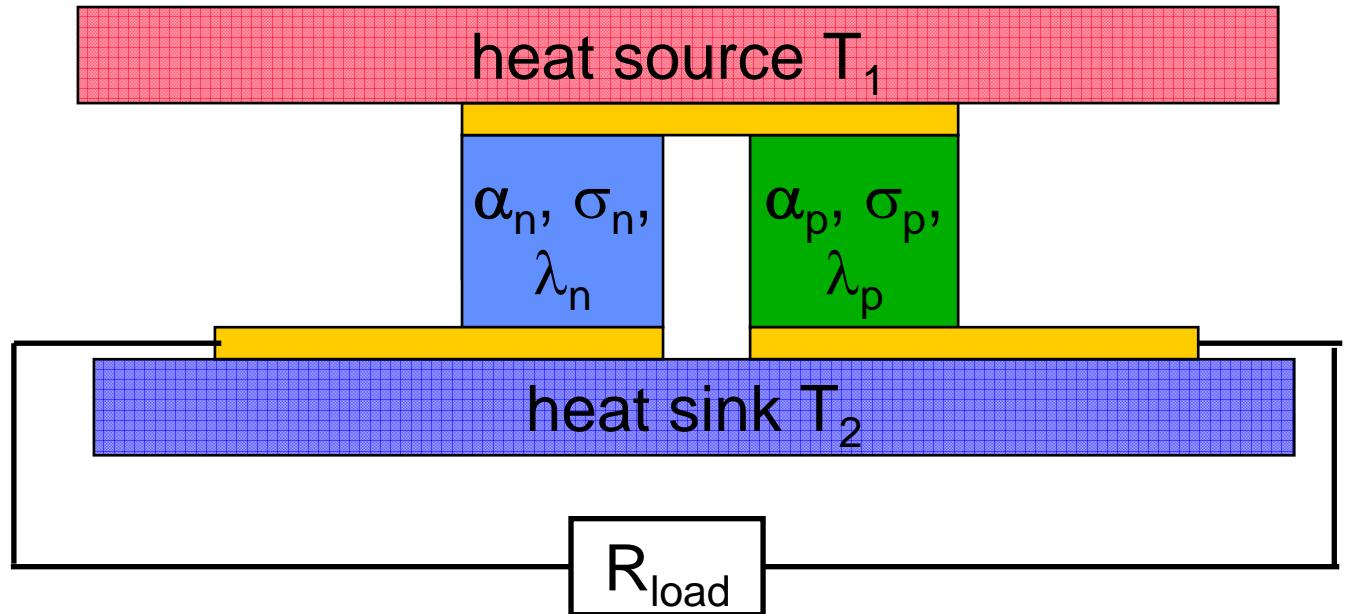


Generators





# Introduction



**Seebeck-Coefficient**

$\alpha_n$  and  $\alpha_p$

**Electrical Conductivity**

$\sigma_n$  and  $\sigma_p$

**Thermal Conductivity**

$\lambda_n$  and  $\lambda_p$

**Dimensionless Figure of Merit ZT**

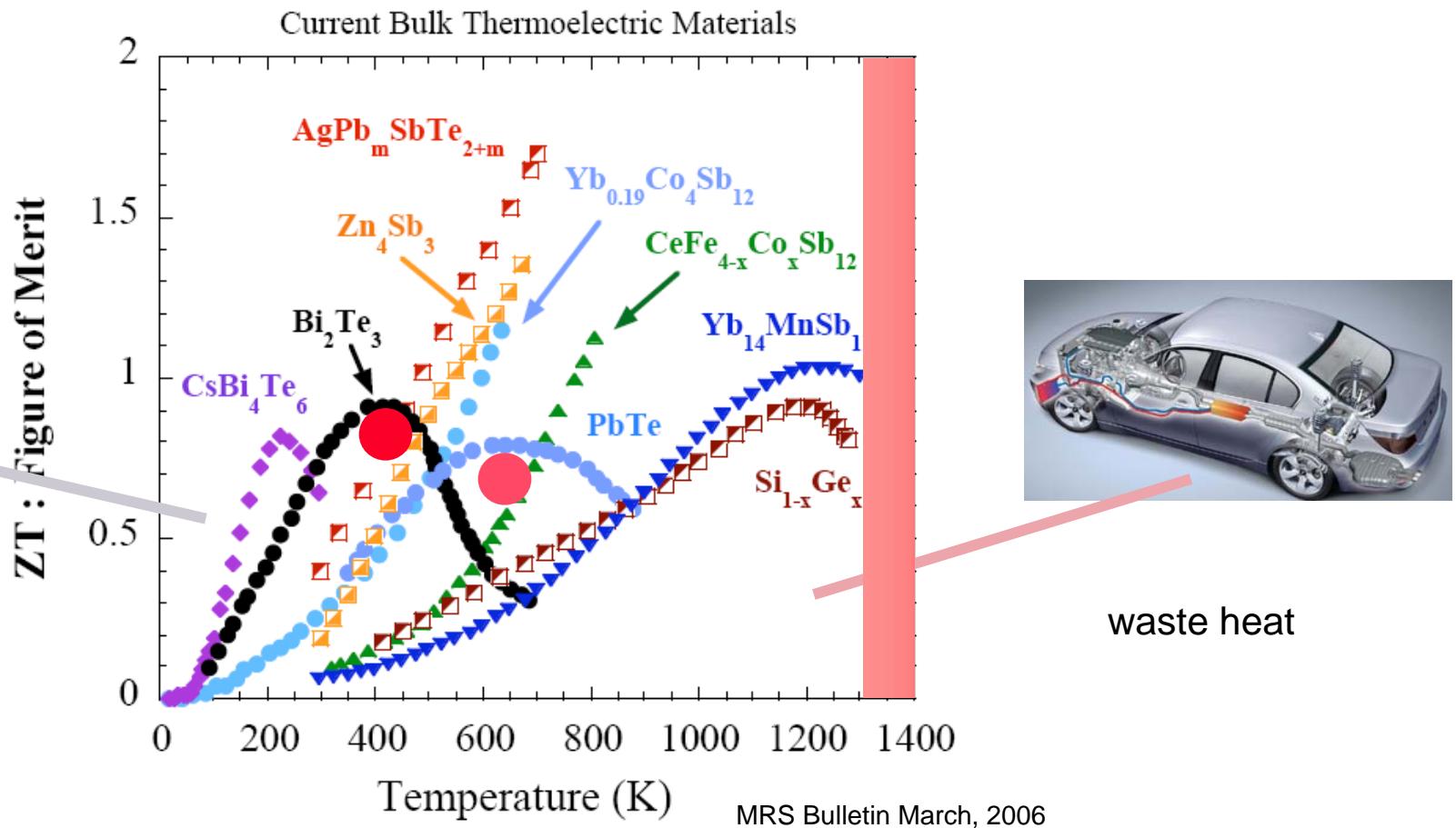
$$ZT = \frac{\sigma \alpha^2}{\lambda} T$$



# Introduction



cooling



# Thermoelectric Effects in ANSYS 9 and higher (Antonova et al., ICT 2005)

Example for COMSOL implementation:

Rearrange equations ...

<u>Field equations</u> $\rho C \frac{\partial T}{\partial t} + \nabla \cdot \mathbf{q} = \dot{\varphi}$ $\nabla \cdot \left( \mathbf{J} + \frac{\partial \mathbf{D}}{\partial t} \right) = 0$ $\mathbf{E} = -\nabla \varphi.$	<u>Constitutive equations</u> $\mathbf{q} = [\Pi] \cdot \mathbf{J} - [\lambda] \cdot \nabla T$ $\mathbf{J} = [\sigma] \cdot (\mathbf{E} - [\alpha] \cdot \nabla T)$ $\mathbf{D} = [\varepsilon] \cdot \mathbf{E},$
<u>Coupled-Field Equations</u>	
$\cancel{\rho C \frac{\partial T}{\partial t} + \nabla \cdot ([\Pi] \cdot \mathbf{J}) - \nabla \cdot ([\lambda] \cdot \nabla T) = \dot{\varphi}}$ $\cancel{\nabla \cdot ([\varepsilon] \nabla \frac{\partial \varphi}{\partial t}) + \nabla \cdot ([\sigma] \cdot [\alpha] \cdot \nabla T) + \nabla \cdot ([\sigma] \cdot \nabla \varphi) = 0}$	

Nomenclature :

$\rho$  = density  
 $C$  = specific heat capacity  
 $T$  = absolute temperature  
 $\dot{\varphi}$  = heat generation rate density  
 $\mathbf{q}$  = heat flux vector  
 $\mathbf{J}$  = electric current density vector  
 $\mathbf{E}$  = electric field intensity vector  
 $\mathbf{D}$  = electric flux density vector  
 $[\lambda]$  = thermal conductivity matrix  
 $[\sigma]$  = electrical conductivity matrix  
 $[\alpha]$  = Seebeck coefficient matrix,  
 $[\Pi] = T[\alpha]$  = Peltier coefficient matrix  
 $[\varepsilon]$  = dielectric permittivity matrix

Antonova, Looman, ICT 2005

5

$$-\vec{\nabla}((\sigma\alpha^2T + \lambda)\vec{\nabla}T) - \vec{\nabla}(\sigma\alpha T\vec{\nabla}V) = \sigma((\vec{\nabla}V)^2 + \alpha\vec{\nabla}T\vec{\nabla}V)$$

$$\vec{\nabla}(\sigma\alpha\vec{\nabla}T) + \vec{\nabla}(\sigma\vec{\nabla}V) = 0$$



## Thermoelectrics in COMSOL:

Rearrange equations ...

$$-\vec{\nabla}((\sigma\alpha^2T + \lambda)\vec{\nabla}T) - \vec{\nabla}(\sigma\alpha T\vec{\nabla}V) = \sigma((\vec{\nabla}V)^2 + \alpha\vec{\nabla}T\vec{\nabla}V)$$
$$\vec{\nabla}(\sigma\alpha\vec{\nabla}T) + \vec{\nabla}(\sigma\vec{\nabla}V) = 0$$

... to match with PDE-application modes  
(coefficient form,  
different notation!)

$$c_a \frac{\partial^2 u}{\partial t^2} + d_a \frac{\partial u}{\partial t} + \nabla \cdot (-c\nabla u - \alpha u + \gamma) + \beta \cdot \nabla u + a u = f \quad \text{in } \Omega$$
$$n \cdot (-c\nabla u - \alpha u + \gamma) + q u = g - h^T \mu \quad \text{on } \partial\Omega$$
$$h u = r \quad \text{on } \partial\Omega$$

## Thermoelectrics in COMSOL:

Thermoelectric coupled field equations

$$-\vec{\nabla}((\sigma\alpha^2T + \lambda)\vec{\nabla}T) - \vec{\nabla}(\sigma\alpha T\vec{\nabla}V) = \sigma((\vec{\nabla}V)^2 + \alpha\vec{\nabla}T\vec{\nabla}V)$$

$$\vec{\nabla}(\sigma\alpha\vec{\nabla}T) + \vec{\nabla}(\sigma\vec{\nabla}V) = 0$$

... example: static thermoelectrics

$$\cancel{c_a \frac{\partial^2 u}{\partial t^2} + d_a \frac{\partial u}{\partial t}} + \nabla \cdot (-c\nabla u - \cancel{\alpha u + \gamma}) + \cancel{\beta \cdot \nabla u + \alpha u} = f \quad \text{in } \Omega$$

$$n \cdot (-c\nabla u - \cancel{\alpha u + \gamma}) + \cancel{q u} = g - h^T \mu \quad \text{on } \partial\Omega$$

$$h u = r \quad \text{on } \partial\Omega$$

# Thermoelectrics in COMSOL:

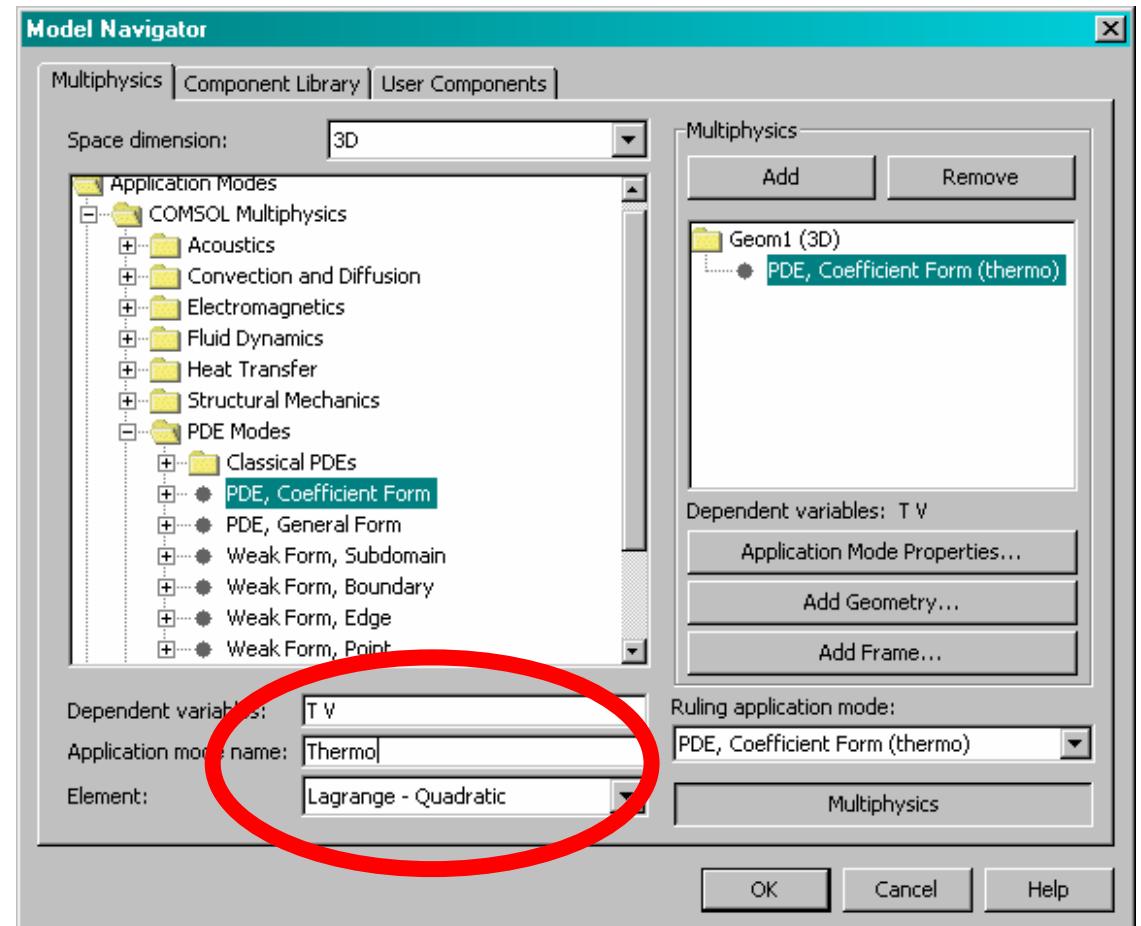
Defining

-Application mode

PDE-Mode, coefficient Form

- Field Variable

$$\vec{u} = \begin{pmatrix} T \\ V \end{pmatrix}$$

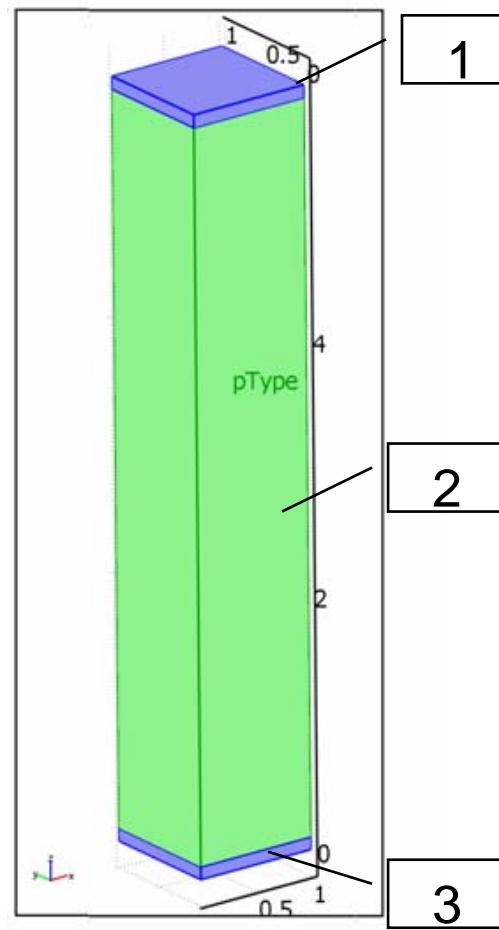


## Thermoelectrics in COMSOL:

Defining model  
geometry, example:  
P-Type thermoelectric leg

1, 3: Copper electrodes  
wxlxh: 1x1x0.1mm<sup>3</sup>

2: p-type thermoelectric leg  
wxlxh: 1x1x5.8mm<sup>3</sup>



		Thermoelectric Material, 2	Electrode (Copper), 1, 3
Seebeck Coefficient	$\alpha$ , V/K	p: 200e-6 n: -200e-6	6.5e-6
Electric conductivity	$\sigma$ , S/m	1.1e5	5.9e8
Thermal conductivity	$\lambda$ , W/m/K	1.6	350
Density	$\rho$ , kg/m <sup>3</sup>	7740	8920
Heat capacity	C, J/kg/K	154.4	385

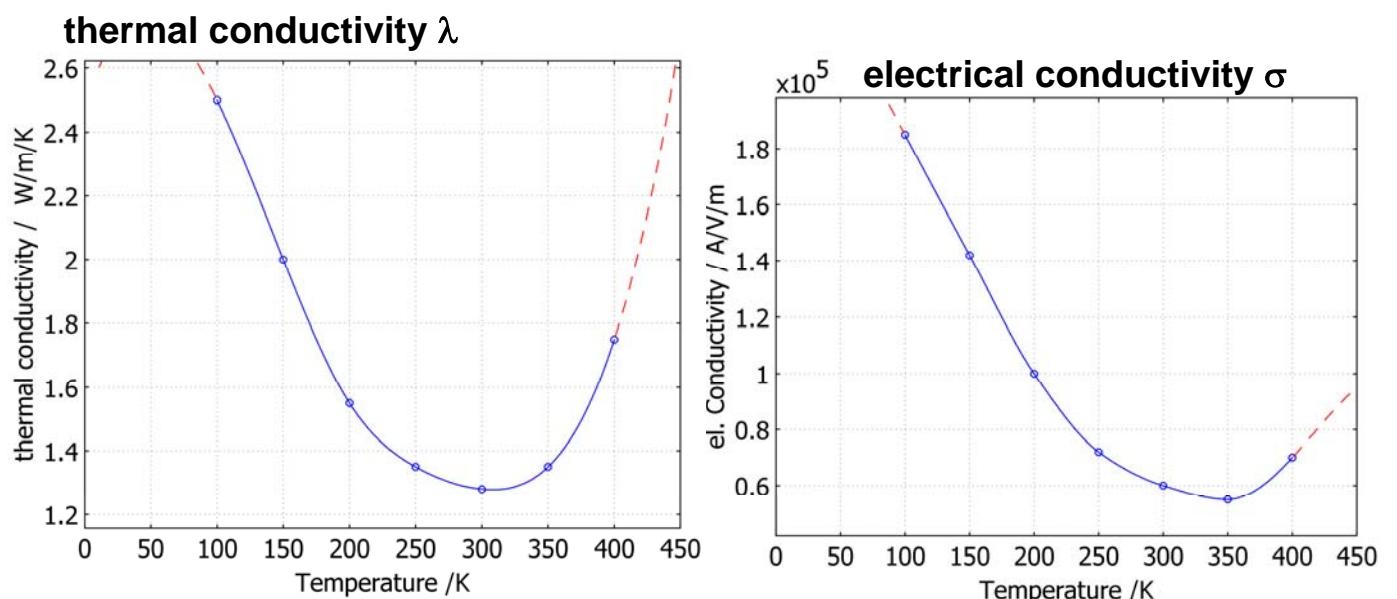
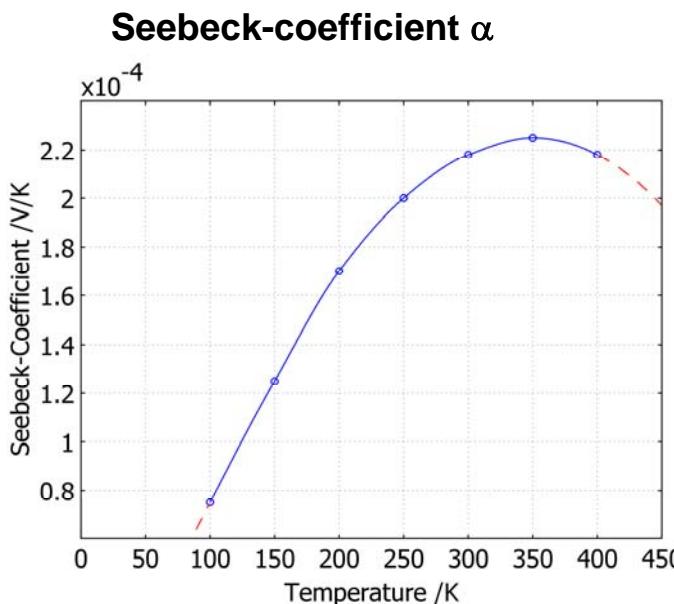
Antonova, Looman, ICT 2005



## Thermoelectrics in COMSOL:

Temperature dependent material properties for p-Bismuth Telluride

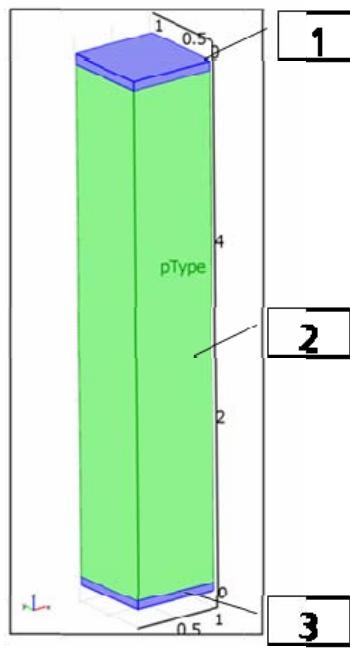
T /K	$\alpha / 10^{-6} \text{V/K}$	$\lambda / \text{W/m/K}$	$\sigma / 10^3 \text{A/V/m}$
100	75	2.5	185
150	125	2	142
200	170	1.55	100
250	200	1.35	72
300	218	1.28	60
350	225	1.35	55
400	218	1.75	70



Seifert, W., Ueltzen, M., Müller, E.; One Dimensional Modelling of Thermoelectric Cooling; phys.stat.sol. (a) 194, No.1, pp 277 – 290; 2002

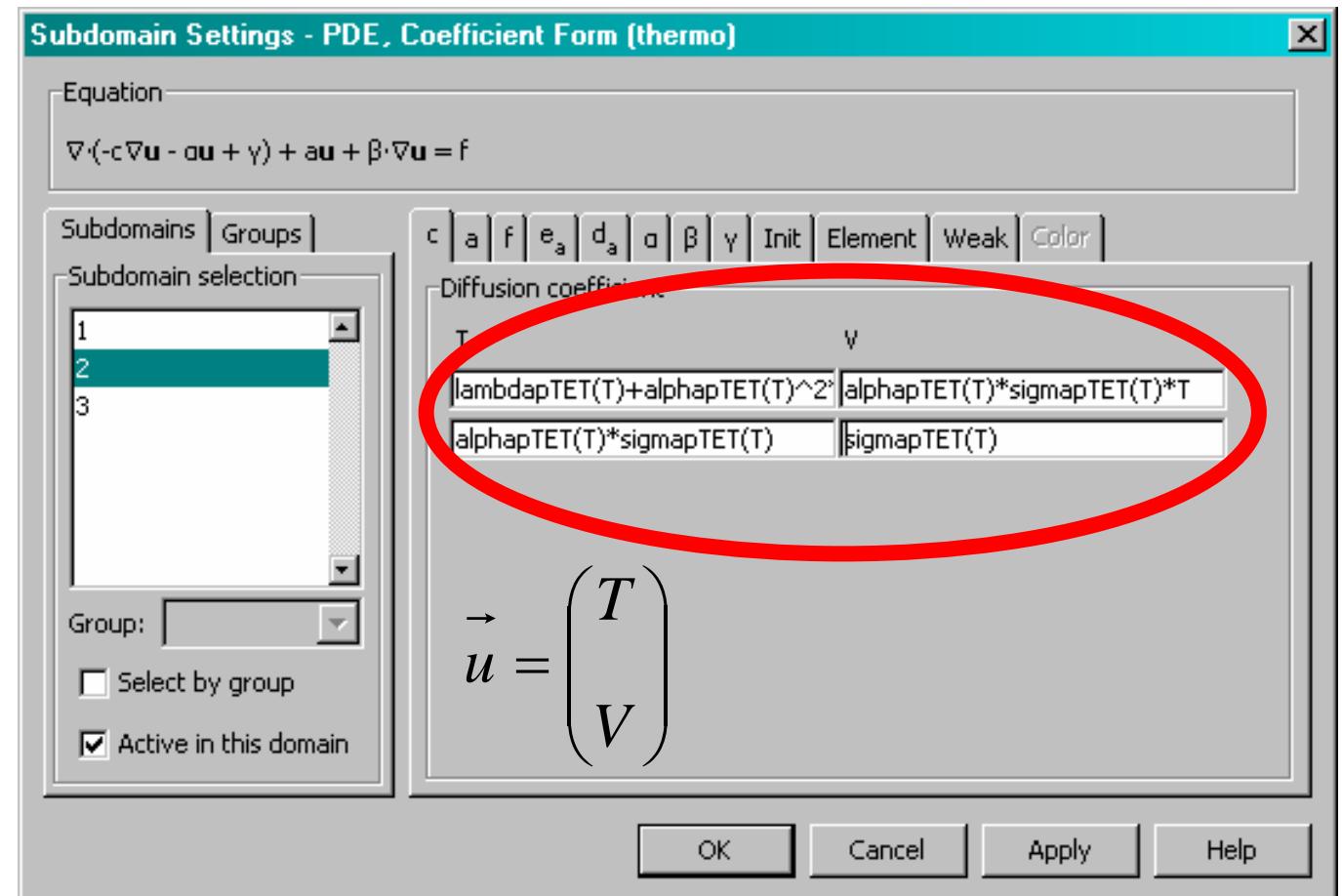


# Thermoelectrics in COMSOL:

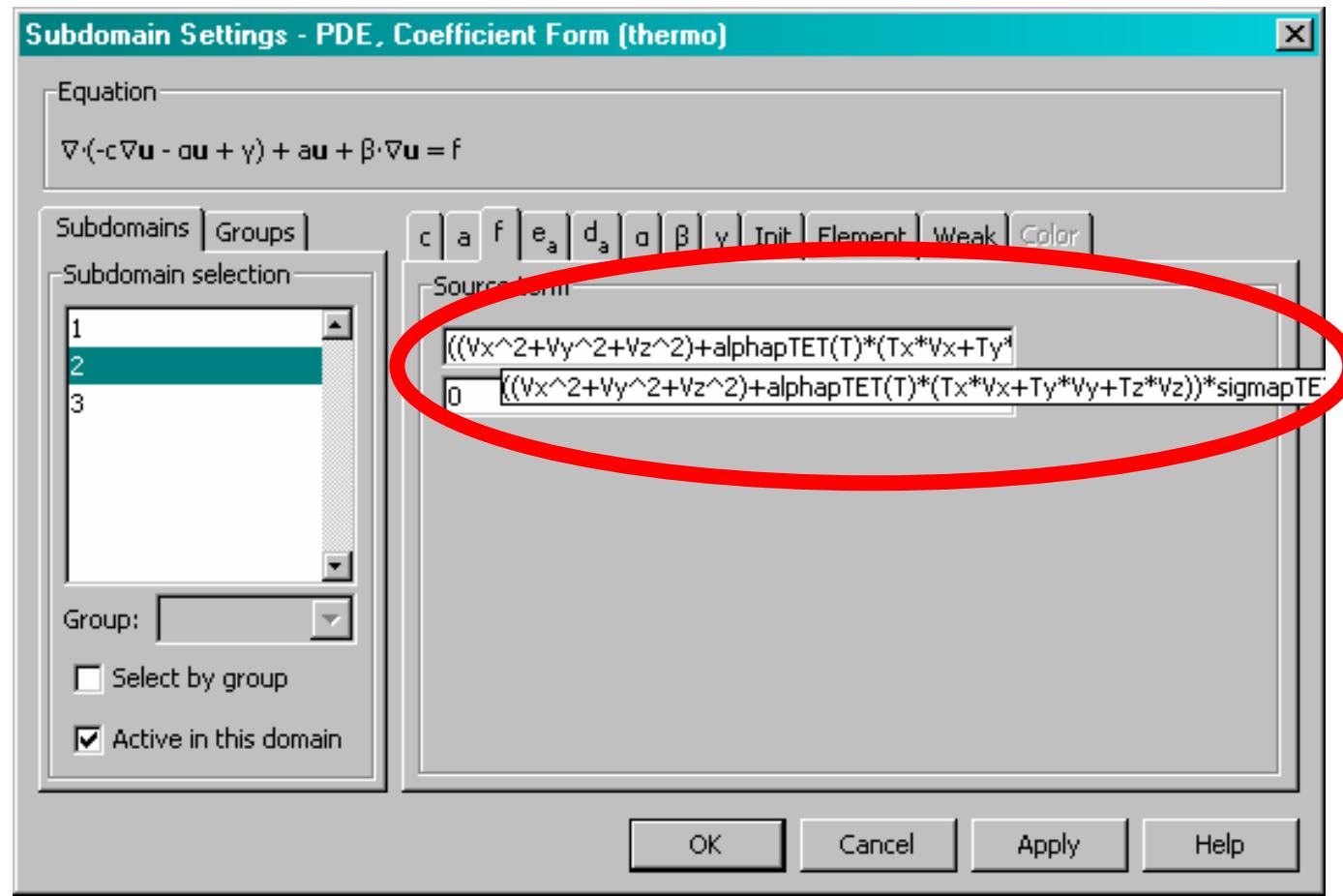
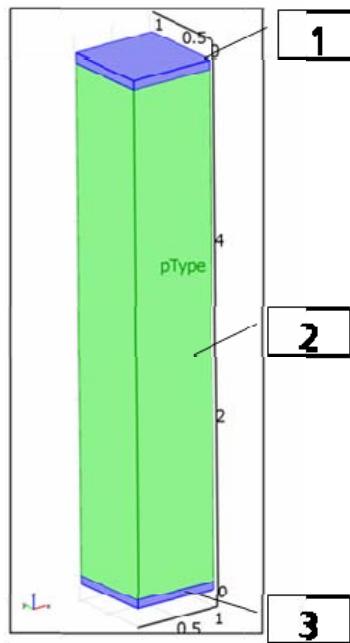


Defining coefficient c:

$$c = \begin{pmatrix} \lambda + \sigma\alpha^2 T & \sigma\alpha T \\ \sigma\alpha & \sigma \end{pmatrix}$$



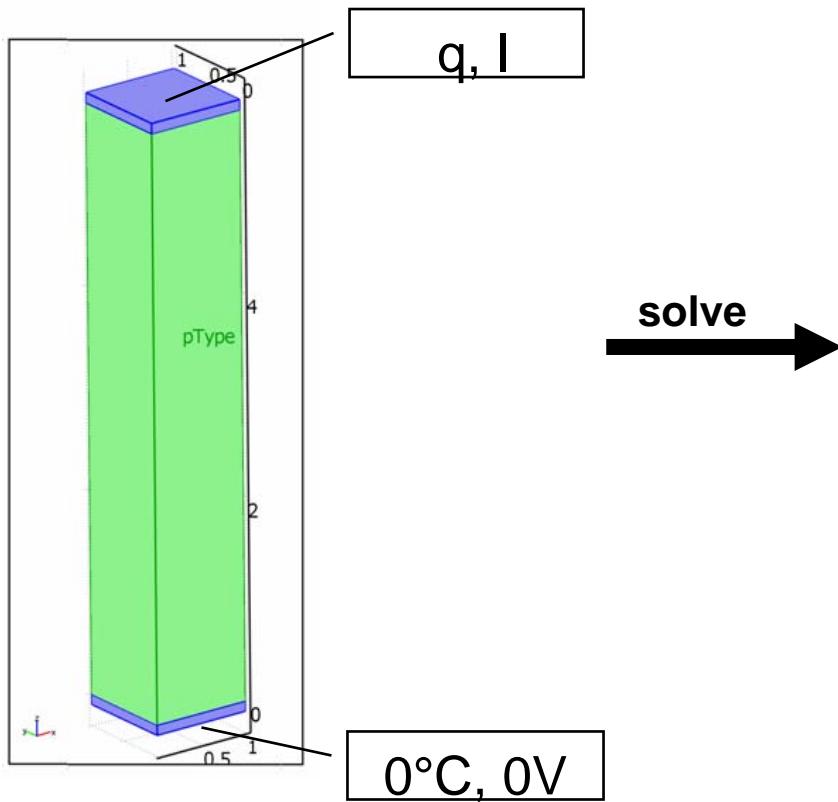
# Thermoelectrics in COMSOL:



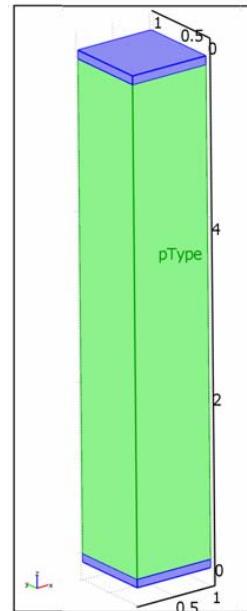
Defining coefficient f

$$f = \begin{pmatrix} \sigma \left( (\vec{\nabla} V)^2 + \alpha \vec{\nabla} T \vec{\nabla} V \right) \\ 0 \end{pmatrix}$$

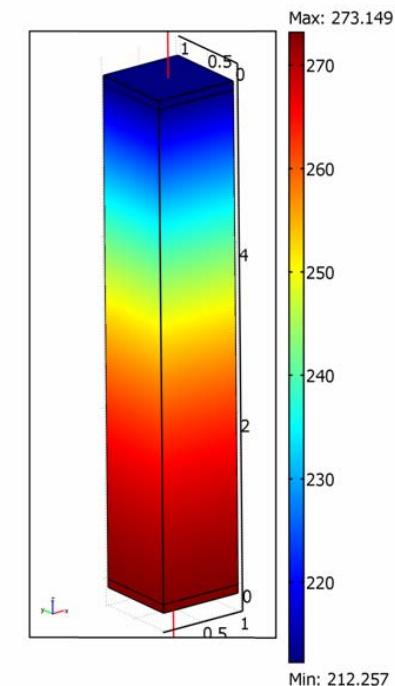
## Thermoelectrics in COMSOL:



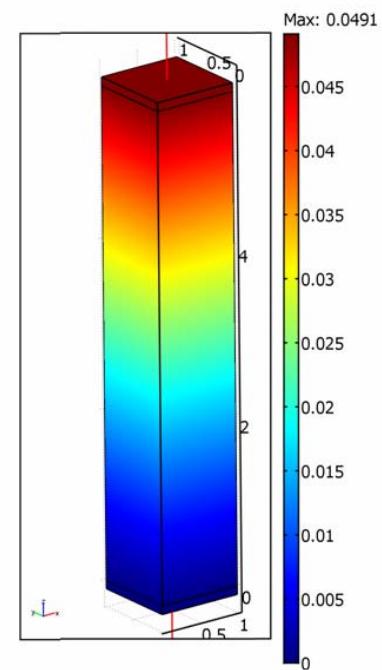
Geometry



Temperature



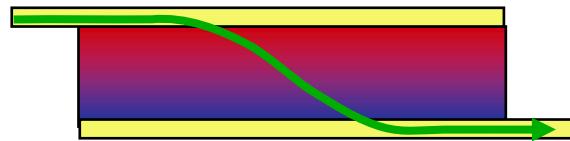
Voltage



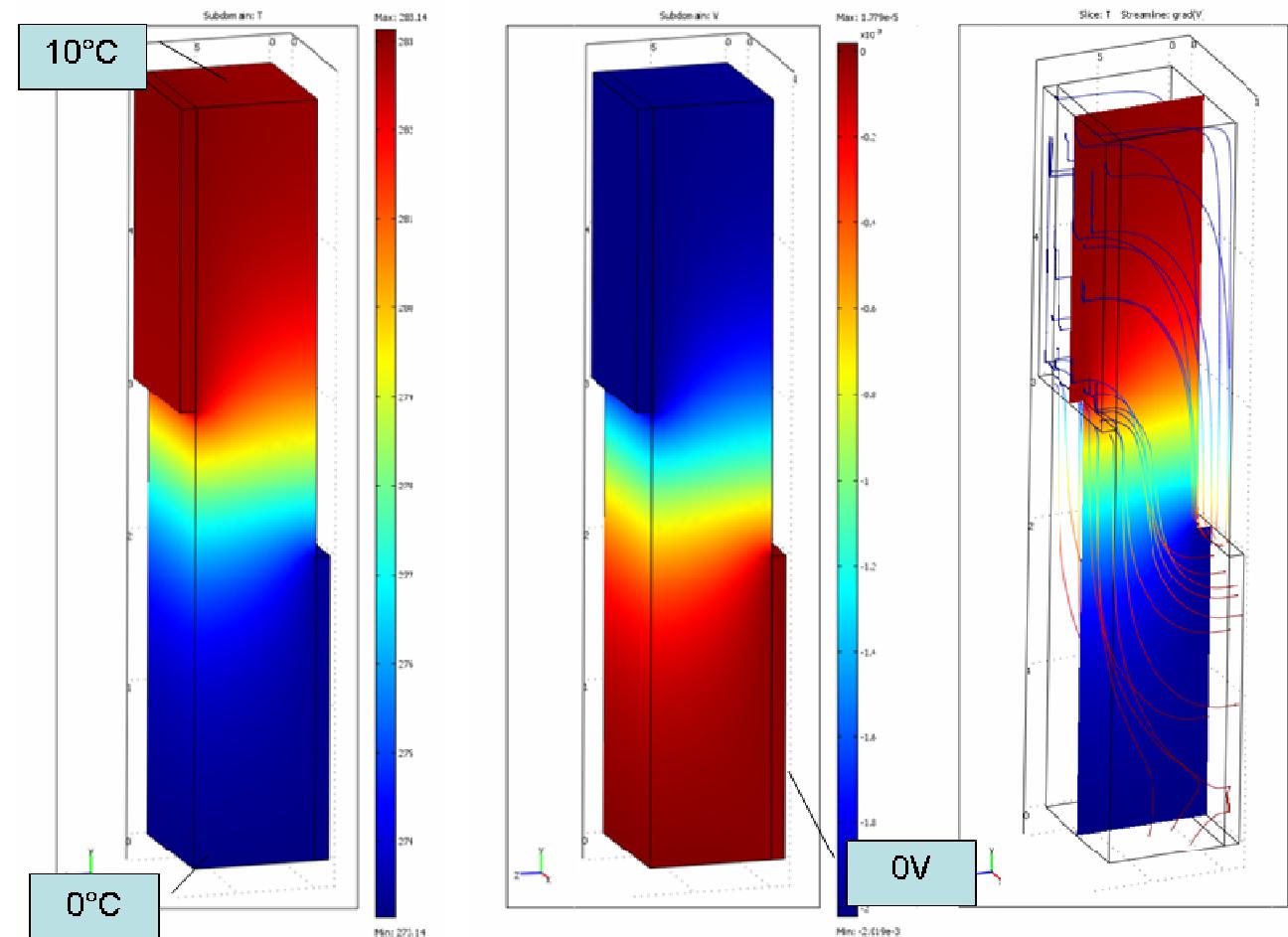
A p-type thermoelectric element is contacted by copper electrodes (left). The base is kept at 0°C and 0V. At the top 0.7A current was applied. Adiabatic boundary conditions were used. The resulting temperature distribution is shown in the center, the voltage is shown right. A temperature difference of nearly 61 K is achieved. The voltage at the upper electrode is 49 mV.



# „complex“ geometries



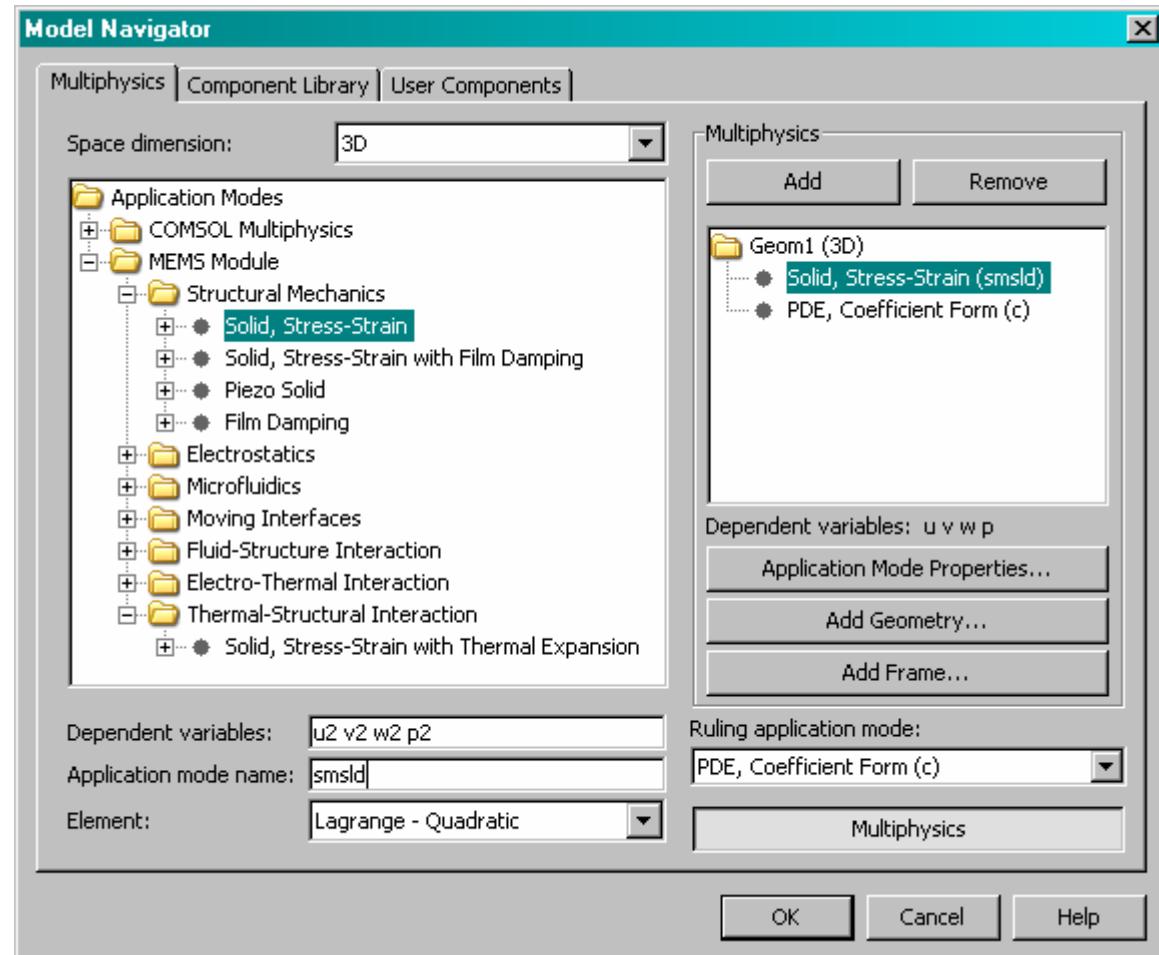
Example for a more “complex” element geometry: The copper electrodes are laterally connected (with respect to the temperature gradient). Left side: Temperature distribution, the top is set to 10°C, the base is at 0°C. The appropriate Voltage is shown in the middle; the left graph shows the voltage color coded electric streamlines and the temperature as a slice plot.



# Thermal- electric- mechanic effects

Temperature  
Voltage  
Displacement  
Stress

- thermoelectric effects
- strain
- thermal expansion
- no piezo-effect

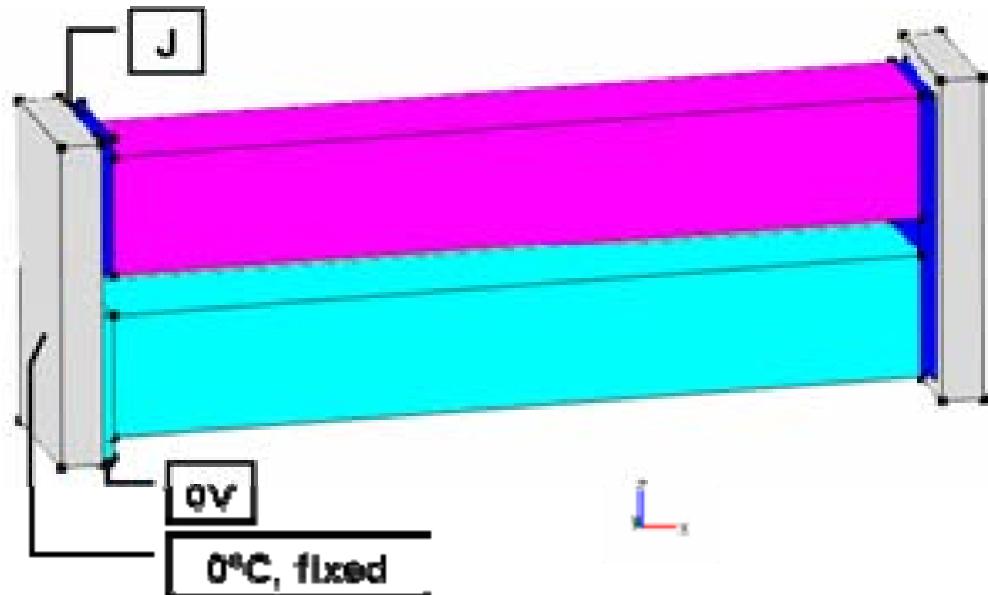


# Thermoelectric and thermomechanic effects

Elastic material properties of  $\text{Bi}_2\text{Te}_3$   $c_{ij}$  in  $10^{11}\text{dyn/cm}^2$  at 280K

$c_{11}$	$c_{66}$	$c_{33}$	$c_{44}$	$c_{13}$	$c_{14}$
6.847	2.335	4.768	2.738	2.704	1.325
Thermal expansion coefficient $a_i / 10^{-6}/\text{K}$ at 300K of $\text{Bi}_2\text{Te}_3$					
$a_x$	$a_y$	$a_z$			
21.3	14.4	14.4			

Landolt-Börnstein; Numerical data; ISBN3540121609; Vol 17f, pp.275, 1983



Thermoelectric material properties		Thermoelectric Material $\text{Bi}_2\text{Te}_3$ based	Electrode (Copper)
Seebeck Coefficient	$\alpha, \text{V/K}$	$p: 200\text{e-6}$ $n: -200\text{e-6}$	$6.5\text{e-6}$
Electric conductivity	$\sigma, \text{S/m}$	$1.1\text{e}5$	$5.9\text{e}8$
Thermal conductivity	$\lambda, \text{W/m/K}$	1.6	350

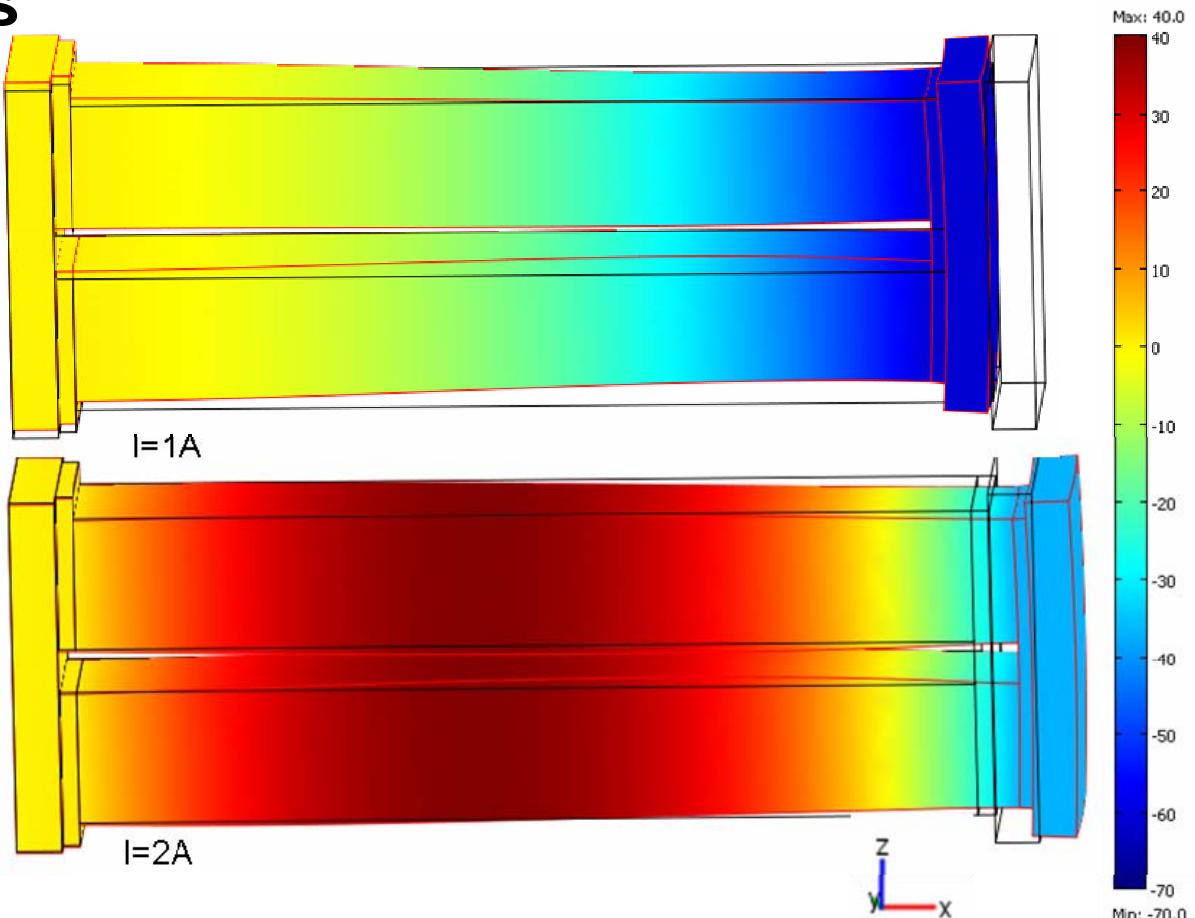
Antonova et al., ICT 2005



# Thermoelectric and thermomechanic effects

Example:  
Displacement due to thermal  
expansion

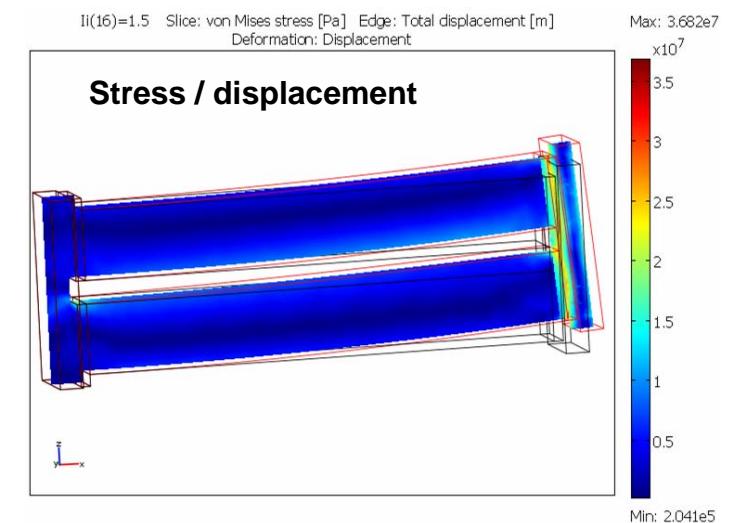
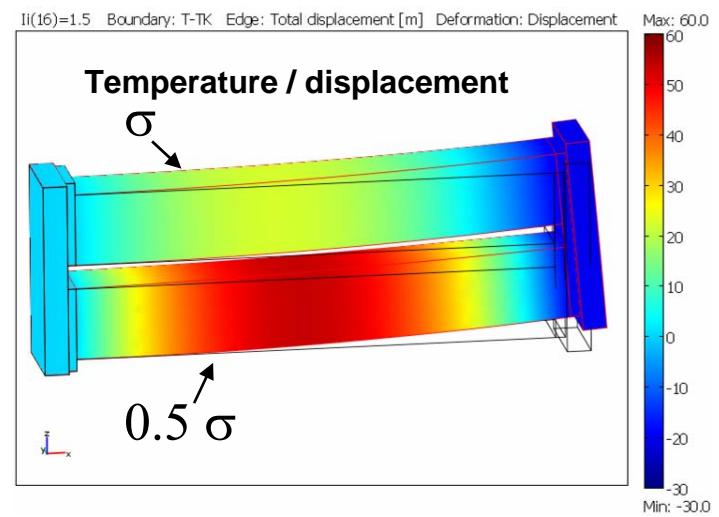
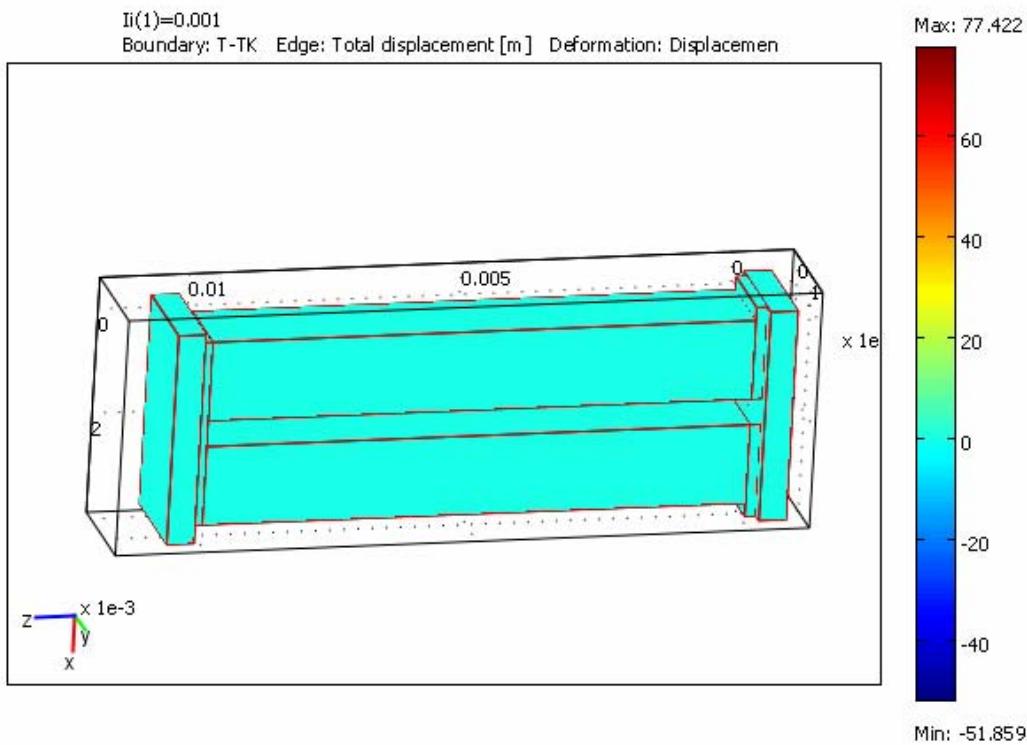
5 microns shrunken at 1A



4 microns expanded at 2A  
(still cooling)

# Thermoelectric and thermomechanic effects

Example: asymmetric material properties



# Summary

Thermoelectric effects in COMSOL for modeling of thermoelectric cooling, generation and sensing

Temperature and position dependent material properties

Anisotropic materials (not shown here for thermoelectrics)

Arbitrary geometries

Graded/ stacked materials

Determination of effective material properties (no quantum effects)

Simultaneous modeling of thermoelectric systems including

- Mechanical effects, strain, stress
- Thermomechanical effects
- Convection (not shown here)
- Radiation (not shown here)
- ...



# Multiphysics Simulation of Thermoelectric Systems

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